

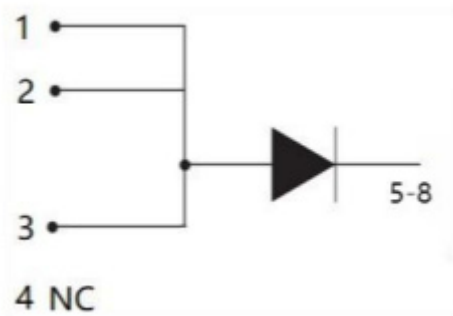
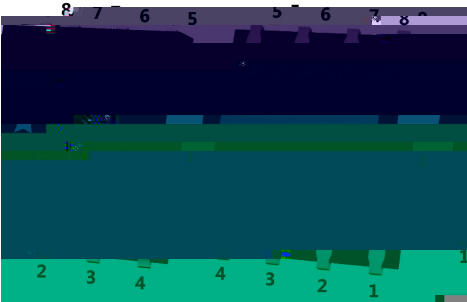
/ Descriptions

PDFN5Ö6 M M E VIF ² g~ || 1
SiC Schottky Barrier Diode in a PDFN5×6 Plastic Package.

/ Features

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Low power loss, high efficiency, HF Product.

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For high frequency, high voltage, high current rectifier diode, freewheeling diode



PIN 1,2,3 χ Anode PIN5-8 χ Cathode PIN 4 χ NC

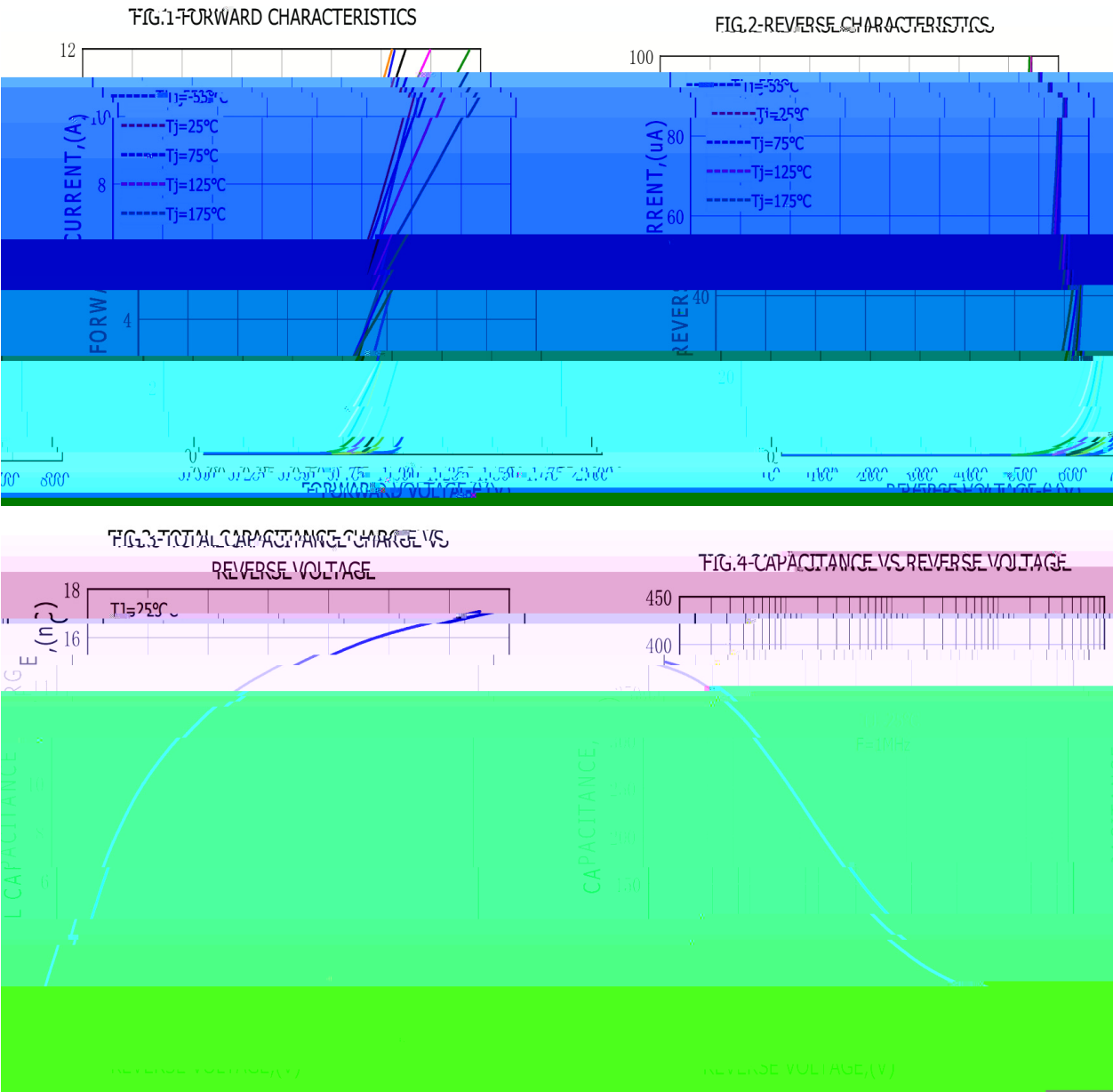
/ Marking

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See Marking Instructions.

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	650	V
Maximum RMS Voltage	V_{RMS}	455	V
Maximum DC blocking Voltage	V_{DC}	650	V
Continuous Forward Current, $T_C=150$	I_F	6	A
Peak forward surge current, $t_p=8.3ms$	I_{FSM}	52	A
Total power dissipation	P_D	53	W
Typical Thermal Resistance Junction to Case	$R_{\theta JC}$	2.8	/W
Operation Junction Temperature and Storage Temperature	T_J, T_{STG}	-55~+175	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_R		650	-	-	V
Forward Voltage	V_F	$I_F=6A \quad T_C=25$	-	1.27	1.5	
		$I_F=6A \quad T_C=175$	-	1.38	1.6	
Instantaneous Reverse Current	I_R Note 1	$V_R=650V \quad T_a=25$	-	4	50	μA
		$V_R=650V \quad T_a=175$	-	200	200	
Total capacitive charge	Q_C	$V_R=650V, I_F=6A$ $di/dt=200A/\mu s$	-	17	-	nC

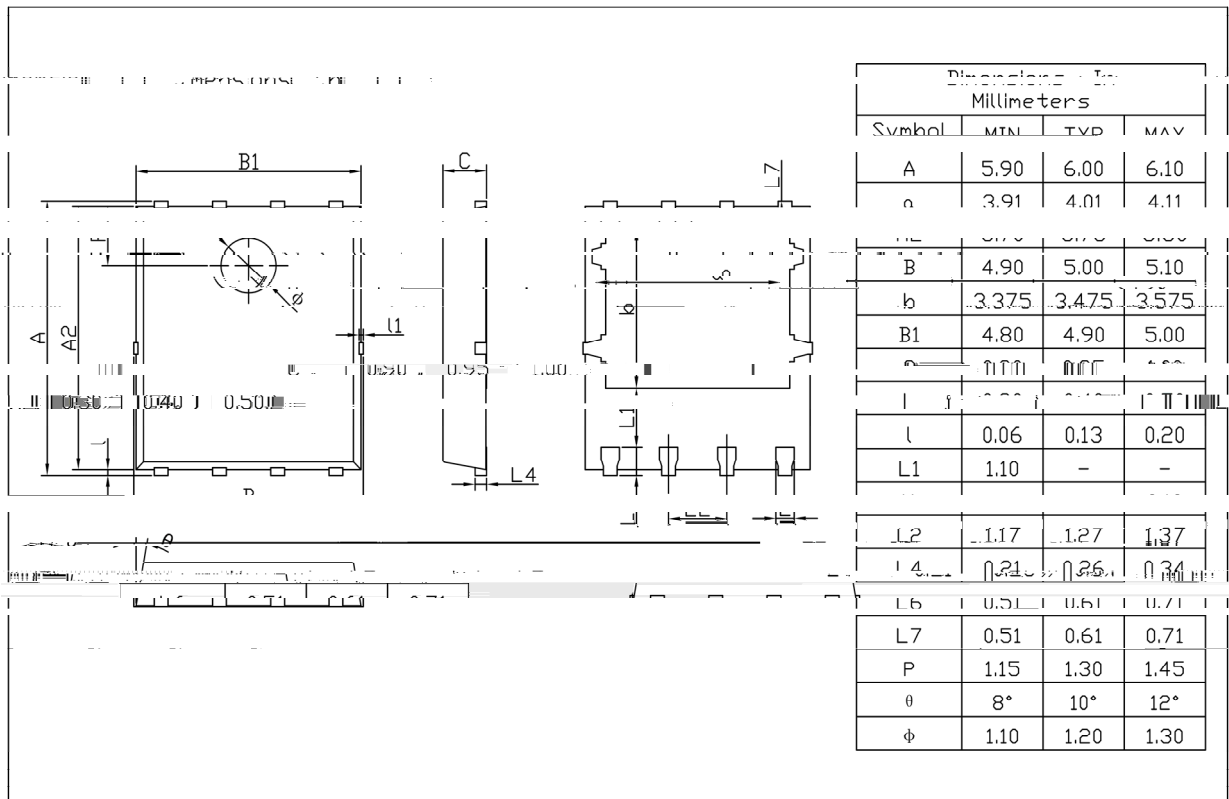
/ Electrical Characteristic Curve



/ Package Dimensions

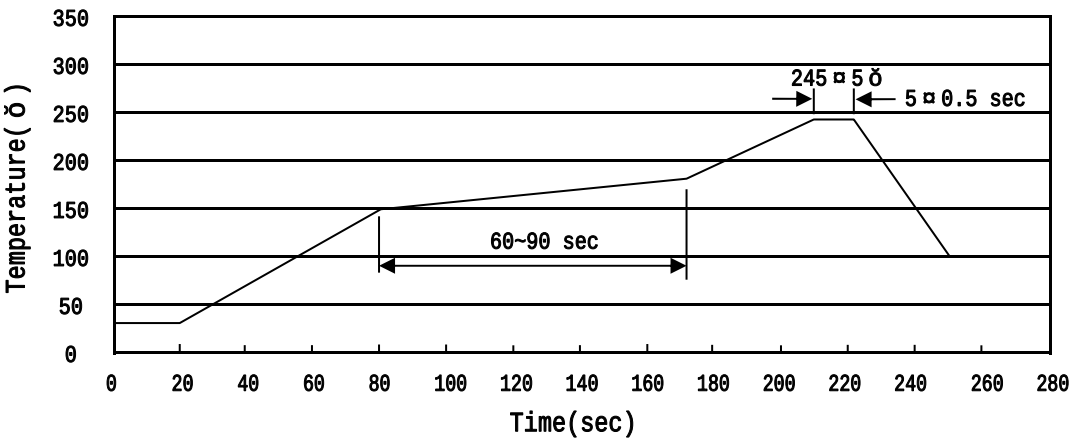
PDFN5 X6

Unit:mm



Rev.01 202209

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



注意

1. 预加热: 150~180℃, Time: 60~90sec;
2. 峰值温度: 245±5℃, 持续时间: 5±0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

1. Preheating: 150~180℃, Time: 60~90sec.
2. Peak Temp.: 245±5℃, Duration: 5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度: 260±5℃, 时间: 10±1 sec. Temp.: 260±5℃ Time: 10±1 sec

/ Packaging SPEC.

包装形式 / REEL

Package Type 封装形式	Units					Dimension (unit: mm)		
	Units/Reel 每盘数量	Reels/Inner Box 盘数/内盒	Units/Inner Box 数量/内盒	Inner Boxes/Outer Box 内盒数/外盒	Units/Outer Box 数量/外盒	Reel	Inner Box	Outer Box
PDFN5×6	5,000	2	10,000	6	60,000	13"×12"	360×360×50	380×335×366

/ Notices